

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

1-2 (cancelled)

3.(original) A production process of light emitting device equipped with a substrate, light emitting layers formed on the substrate, and an insulator layer mutually partitioning the light emitting layers;

wherein the production process includes a process of forming the insulator layer by a thermal transfer method.

4.(original) A production process of a light emitting device according to claim 3, which includes;

a process of forming the insulator layer on a transfer member by a thermal transfer method, and

a process of transferring the insulator layer which has been formed on the transfer member, to the substrate.

5-6 (cancelled)

7.(original) A production process of a light emitting device according to claim 3;

wherein the light emitting layers contain a light emitting material emitting light by impressing electric field.

8.(original) A production process of a light emitting device according to claim 4;

wherein the light emitting layers contain a light emitting material emitting light by impressing electric field.

9-10 (cancelled)

11.(original) A production process of a light emitting device according to claim 3;

wherein the substrate is composed of a resin.

12.(original) A production process of a light emitting device according to claim 4;

wherein the substrate is composed of a resin.

13-14 (cancelled)

15.(original) A production process of a light emitting device according to claim 7;

wherein the substrate is composed of a resin.

16.(original) A production process of a light emitting device according to claim 8;

wherein the substrate is composed of a resin.